SCBS030E - SEPTEMBER 1988 - REVISED MARCH 2003

- Operating Voltage Range of 4.5 V to 5.5 V
- State-of-the-Art BiCMOS Design Significantly Reduces I<sub>CCZ</sub>
- Output Ports Have Equivalent 33-Ω Series Resistors, So No External Resistors Are Required
- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers

#### description/ordering information

These octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. Together with the SN74BCT2241 and the 'BCT2244 devices, these devices provide the choice of selected combinations of inverting and noninverting outputs, symmetrical active-low output-enable ( $\overline{OE}$ ) inputs, and complementary OE and  $\overline{OE}$  inputs. These devices feature high fan-out and improved fan-in.

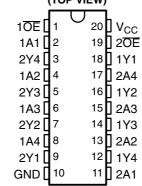
The 'BCT2240 devices are organized as two 4-bit line drivers with separate output-enable  $(\overline{OE})$  inputs. When  $\overline{OE}$  is low, the device passes data from the A inputs to the Y outputs. When  $\overline{OE}$  is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$ 

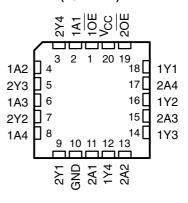
through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The outputs, which are designed to source or sink up to 12 mA, include 33- $\Omega$  series resistors to reduce overshoot and undershoot.

#### SN54BCT2240 . . . J OR W PACKAGE SN74BCT2240 . . . DB, DW, N,OR NS PACKAGE (TOP VIEW)



# SN54BCT2240 . . . FK PACKAGE (TOP VIEW)



#### ORDERING INFORMATION

TA	PACKA	.GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	PDIP – N Tube		SN74BCT2240N	SN74BCT2240N	
	SOIC - DW	Tube	SN74BCT2240DW	DOTO040	
0°C to 70°C	SOIC - DW	Tape and reel	SN74BCT2240DWR	BCT2240	
	SOP – NS Tape and reel		SN74BCT2240NSR	BCT2240	
	SSOP – DB Tape and reel		SN74BCT2240DBR	BA240	
	CDIP – J Tube		SNJ54BCT2240J	SNJ54BCT2240J	
-55°C to 125°C	CFP – W	Tube	SNJ54BCT2240W	SNJ54BCT2240W	
	LCCC - FK	Tube	SNJ54BCT2240FK	SNJ54BCT2240FK	

<sup>&</sup>lt;sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

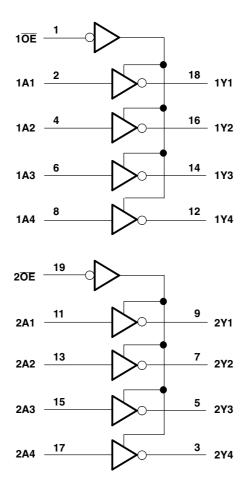


SCBS030E - SEPTEMBER 1988 - REVISED MARCH 2003

# FUNCTION TABLE (each buffer)

INPL	JTS	OUTPUT
ŌĒ	Α	Υ
L	Н	L
L	L	Н
Н	Χ	Z

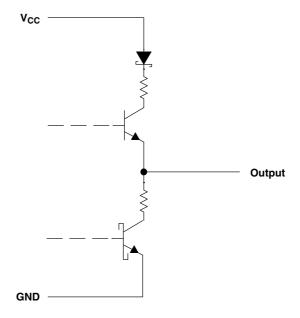
### logic diagram (positive logic)





SCBS030E - SEPTEMBER 1988 - REVISED MARCH 2003

### schematic of Y outputs



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$	oled or power-off state, V <sub>O</sub> state, V <sub>O</sub>	-0.5 V to 7 V -0.5 V to 5.5 V -0.5 V to V <sub>CC</sub> -30 mA 24 mA 70°C/W 58°C/W 69°C/W
		60°C/W
Storage temperature range, T <sub>stg</sub>		

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



## SN54BCT2240, SN74BCT2240 OCTAL BUFFERS AND LINE/MOS DRIVERS WITH 3-STATE OUTPUTS

SCBS030E - SEPTEMBER 1988 - REVISED MARCH 2003

### recommended operating conditions (see Note 3)

		SN	4BCT22	240	SN74BCT2240			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
$V_{CC}$	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
$V_{IH}$	High-level input voltage	2			2			٧
$V_{IL}$	Low-level input voltage			8.0			0.8	٧
I <sub>IK</sub>	Input clamp current			-18			-18	mA
I <sub>OH</sub>	High-level output current			-12			-12	mA
I <sub>OL</sub>	Low-level output current			12			12	mA
T <sub>A</sub>	Operating free-air temperature	-55		125	0		70	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS		SN	54BCT22	240	SN74BCT2240			
PARAMETER	I E	TEST CONDITIONS			MAX	MIN	TYP†	MAX	UNIT
$V_{IK}$	$V_{CC} = 4.5 \text{ V},$	$I_I = -18 \text{ mA}$			-1.2			-1.2	V
V	V 45V	$I_{OH} = -1 \text{ mA}$	2.4	3.3		2.4	3.3		٧
V <sub>OH</sub>	V <sub>CC</sub> = 4.5 V	$I_{OH} = -12 \text{ mA}$	2	3.2		2	3.2		V
V	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 1 mA		0.15	0.5		0.15	0.5	V
V <sub>OL</sub>		$I_{OL} = 12 \text{ mA}$		0.35	0.8		0.35	8.0	V
lį	$V_{CC} = 5.5 V$ ,	$V_I = 7 V$			0.1			0.1	mA
I <sub>IH</sub>	$V_{CC} = 5.5 V$ ,	$V_{I} = 2.7 \text{ V}$			20			20	μΑ
I <sub>IL</sub>	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = 0.5 V			-1			-1	mA
l <sub>OZH</sub>	$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.7 V			50			50	μΑ
l <sub>OZL</sub>	$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 0.5 V			-50			-50	μΑ
l <sub>os</sub> ‡	$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 0	-100		-225	-100		-225	mA
Іссн	$V_{CC} = 5.5 \text{ V},$	Outputs open		19	32		19	32	mA
I <sub>CCL</sub>	$V_{CC} = 5.5 \text{ V},$	Outputs open		46	76		46	76	mA
I <sub>CCZ</sub>	$V_{CC} = 5.5 \text{ V},$	Outputs open		6	8		6	8	mA

 $<sup>^{\</sup>dagger}$  All typical values are at  $V_{CC}$  = 5 V,  $T_{A}$  = 25°C.

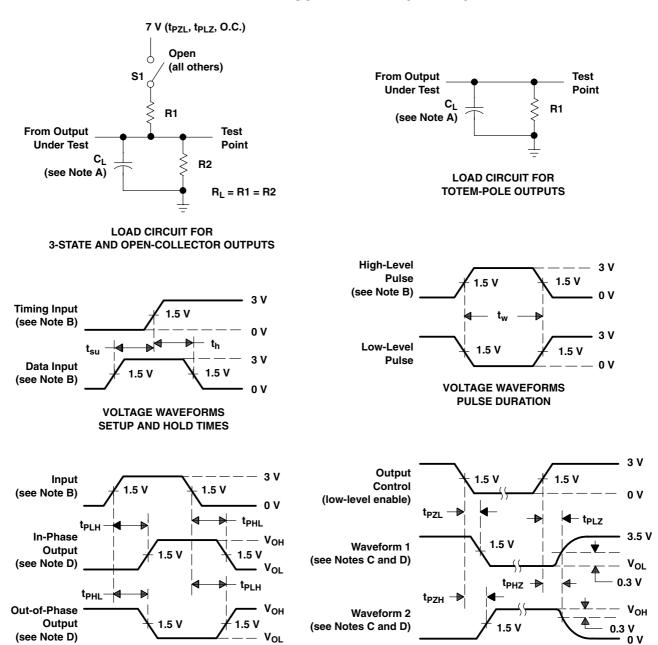
# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ =50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO		$V_{CC} = 5 \text{ V},$ $T_A = 25^{\circ}\text{C}$ SN54BCT2240 SN74BCT22				CT2240	UNIT	
	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	А	Y	0.5	3.4	4.8	0.5	6.3	0.5	5.7	
t <sub>PHL</sub>			0.5	2.8	4	0.5	4.6	0.5	4.4	ns
t <sub>PZH</sub>	ŌĒ	Y	2.6	6.2	8.2	2.6	10.1	2.6	9.3	
t <sub>PZL</sub>			4.3	8.8	10.9	4.3	12.9	4.3	12.4	ns
t <sub>PHZ</sub>	ŌĒ	V	2	5.3	7.1	2	9.2	2	8.7	ns
t <sub>PLZ</sub>	OE	Ť	2.2	6.7	8.5	2.2	12.2	2.2	10.6	115



<sup>†</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

#### PARAMETER MEASUREMENT INFORMATION



## VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES (see Note D)

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $t_f = t_f \leq$  2.5 ns, duty cycle = 50%.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.
- $\hbox{E. \ \ } When \ measuring \ propagation \ delay \ times \ of \ 3-state \ outputs, \ switch \ S1 \ is \ open.$
- F. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



14-Oct-2025

www.ti.com

#### PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
5962-9093901M2A	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9093901M2A SNJ54BCT 2240FK
5962-9093901MRA	Active	Production	CDIP (J)   20	20   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9093901MR A SNJ54BCT2240J
SNJ54BCT2240FK	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9093901M2A SNJ54BCT 2240FK
SNJ54BCT2240FK.A	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9093901M2A SNJ54BCT 2240FK
SNJ54BCT2240J	Active	Production	CDIP (J)   20	20   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9093901MR A SNJ54BCT2240J
SNJ54BCT2240J.A	Active	Production	CDIP (J)   20	20   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9093901MR A SNJ54BCT2240J

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.



## **PACKAGE OPTION ADDENDUM**

www.ti.com 14-Oct-2025

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

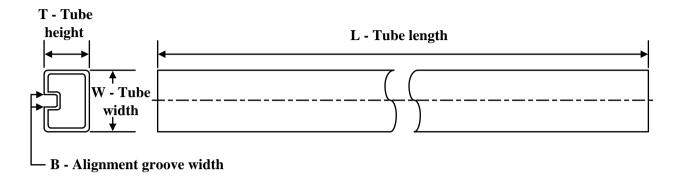
Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

## **PACKAGE MATERIALS INFORMATION**

www.ti.com 23-May-2025

### **TUBE**



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9093901M2A	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54BCT2240FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54BCT2240FK.A	FK	LCCC	20	55	506.98	12.06	2030	NA

### 14 LEADS SHOWN



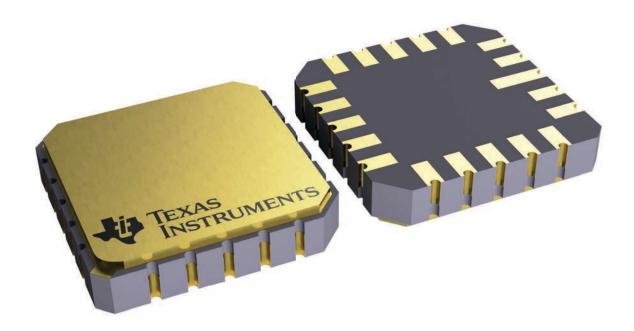
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



**INSTRUMENTS** www.ti.com

### IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2025. Texas Instruments Incorporated